

MAQ591

item can replace **BFQ591**



Approved by:
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SPECIFICATION

PRODUCT: NPN 7.0GHz wideband transistor

MODEL: MAQ591 S OT89

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FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

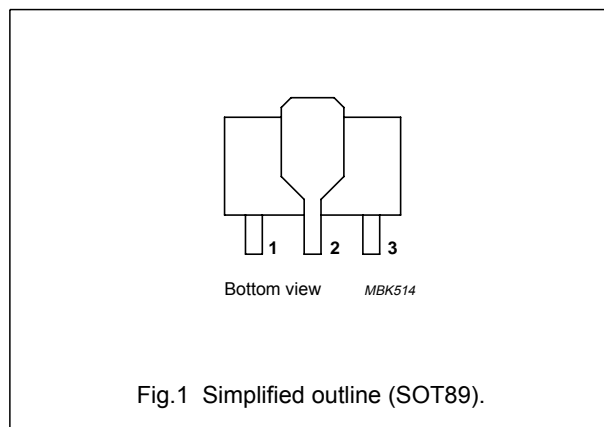
Intended for applications in the GHz range such as MATV or CATV amplifiers and RF communications subscribers equipment.

DESCRIPTION

NPN wideband transistor in a SOT89 plastic package.

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	–	15	V
I_C	collector current (DC)		–	–	200	mA
P_{tot}	total power dissipation	$T_s \leq 90\text{ }^\circ\text{C}$; note 1	–	–	2.25	W
h_{FE}	DC current gain	$I_C = 70\text{ mA}$; $V_{CE} = 8\text{ V}$	60	90	250	
C_{re}	feedback capacitance	$I_C = 0$; $V_{CB} = 12\text{ V}$; $f = 1\text{ MHz}$	–	0.8	–	pF
f_T	transition frequency	$I_C = 70\text{ mA}$; $V_{CE} = 12\text{ V}$; $f = 1\text{ GHz}$	–	7	–	GHz
G_{UM}	maximum unilateral power gain	$I_C = 70\text{ mA}$; $V_{CE} = 12\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	–	11	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 70\text{ mA}$; $V_{CE} = 12\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	–	10	–	dB

Note

1. T_s is the temperature at the soldering point of the collector pin.

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CEO}	collector-emitter voltage	open base	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	3	V
I_C	collector current (DC)		–	200	mA
P_{tot}	total power dissipation	$T_s \leq 90\text{ °C}$; note 1	–	2.25	W
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	175	°C

Note

- T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	$T_s \leq 90\text{ °C}$; note 1	38	K/W

Note

- T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

T_j = 25 °C; unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)CBO}	collector-base breakdown voltage	I _C = 0.1 mA; I _E = 0	–	–	20	V
V _{(BR)CES}	collector-emitter breakdown voltage	I _C = 0.1 mA; I _B = 0	–	–	15	V
V _{(BR)EBO}	emitter-base breakdown voltage	I _E = 0.1 mA; I _C = 0	–	–	3	V
I _{CBO}	collector-base leakage current	I _E = 0; V _{CB} = 10	–	–	100	nA
h _{FE}	DC current gain	I _C = 70 mA ; V _{CE} = 8 V	60	90	250	
C _{re}	feedback capacitance	I _C = 0; V _{CB} = 12 V; f = 1 MHz	–	0.8	–	pF
f _T	transition frequency	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz	–	7	–	GHz
G _{UM}	maximum unilateral power gain; note 1	I _C = 70 mA; V _{CE} = 12 V; T _{amb} = 25 °C f = 900 MHz f = 2 GHz	–	11 5.5	–	dB dB
s ₂₁ ²	insertion power gain	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz; T _{amb} = 25 °C	–	10	–	dB
V _o	output voltage	note 2	–	700	–	mV

Notes

- G_{UM} is the maximum unilateral power gain, assuming s₁₂ is zero and $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)}$ dB.
- d_{im} = 60 dB (DIN45004B); V_p = V_o; V_q = V_o – 6 dB; f_p = 795.25 MHz; f_q = 803.25 MHz; f_r = 803.25 MHz; measured at f_(p+q+r) = 793.25 MHz.

